CyberOptics Presents Best Practices for Monitoring Humidity in Immersion Scanner Reticle Environments

Poster session at SPIE Advanced Lithography conference highlights ways to reduce reticle haze effects; sensor saves time and expenses while improving yields

Minneapolis, MN — Feb. 9, 2016— CyberOptics® Corporation (NASDAQ: CYBE), a leading global developer and manufacturer of high precision 3D sensing technology solutions, will present at the SPIE Advanced Lithography 2016, the premier conference for the lithography community, Feb. 21-25, 2016 at the San Jose Marriott and Convention Center, San Jose, California.

A technical poster session on Wed., Feb. 24 at 6 p.m. will feature Allyn Jackson, U.S. and Europe Sales & Field Application Engineer for CyberOptics, discussing "Best practices for monitoring humidity in immersion scanner reticle environments to reduce reticle haze effects."

For individual measurements in semiconductor fab processes, legacy methods are not real-time, can be complicated or inefficient, and can be costly when tools need to be taken off-line for various processes.

CyberOptics' ReticleSense® Auto Multi Sensor (AMSR) can measure humidity in all locations of the reticle environment. In immersion scanner environments for example, monitoring humidity is critical in reducing Reticle Haze. Haze is an adverse effect on reticles caused by a combination of Mask residue, 193nm light and H2O. AMSR can monitor humidity in the total reticle environment and detect any place where H2O is exposed to the reticle. AMSR speeds leveling, vibration and Relative Humidity (RH) measurement to help save significant time and expenses. Controlling particles, inclination, humidity and vibration are all important factors in increasing yield and reducing downtime.

In booth # 308, the company will showcase CyberOptics' AMSR as well as ReticleSense Airborne Particle Sensors (APSRQ), the most efficient and effective wireless measurement devices for airborne particles.

About the CyberOptic WaferSense and ReticleSense Line

The WaferSense measurement portfolio including the Auto Leveling System (ALS), the Auto Gapping System (AGS), the Auto Vibration System (AVS), the Auto Teaching System (ATS), the Airborne Particle Sensor (APS), the next-generation Airborne Particle Sensor (APS2) and the new Auto Multi Sensor (AMS) are available in various wafer shaped form factors depending on the device, including 150mm, 200mm, 300mm and 450mm wafer sizes. The ReticleSense measurement portfolio including the Airborne Particle Sensor (APSR & APSRQ) and next-generation APS2, the Auto Leveling System (ALSR) and the new Auto Multi Sensor (AMSR) are available in a reticle shaped form factor.

For more information about the entire line of CyberOptics solutions please visit the company's website at www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (NASDAQ: CYBE) is a leading global developer and manufacturer of high precision sensing technology solutions. CyberOptics sensors are being used in general purpose metrology and 3D scanning, surface mount technology (SMT) and semiconductor markets to significantly improve yields and productivity. By leveraging its leading edge technologies, the company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of its key vertical segments. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; expectations regarding LDI and its impact on our operations; integration risks associated with LDI and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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